Advance Information

Power MOSFET, N-Channel, SUPERFET® III, FAST

650 V, 40 A, 64 m Ω

Description

SUPERFET III MOSFET is ON Semiconductor's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This advanced technology is tailored to minimize conduction loss, provide superior switching performance, and withstand extreme dv/dt rate. Consequently, SUPERFET III MOSFET is suitable for various AC/DC power conversion for system miniaturization and higher efficiency.

The Power88 package is an ultra-slim surface-mount package (1 mm high) with a low profile and small footprint (8 x 8 mm²). SUPERFET III MOSFET in a Power88 package offers excellent switching performance due to lower parasitic source inductance and separated power and drive sources. Power88 offers Moisture Sensitivity Level 1 (MSL 1).

Features

- 700 V @ T_J= 150°C
- Typ. $R_{DS(on)} = 56 \text{ m}\Omega$
- Ultra Low Gate Charge (Typ. $Q_g = 77 \text{ nC}$)
- Low Effective Output Capacitance (Typ. C_{oss(eff.)} = 769 pF)
- 100% Avalanche Tested
- These Devices are Pb-Free and are RoHS Compliant

Applications

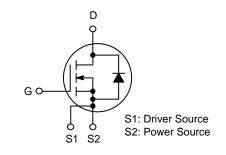
- Telecom / Server Power Supplies
- Industrial Power Supplies
- UPS / Solar



ON Semiconductor®

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V _{DSS}	R _{DS(ON)} MAX	I _D MAX
650 V	64 mΩ @ 10 V	40 A





MARKING DIAGRAM

&Z&3&K NTMT 064N65S3H

&Z = Assembly Plant Code &3 = Data Code (Year & Week)

= Lot

NTMT064N65S3H = Specific Device Code

ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

This document contains information on a new product. Specifications and information herein are subject to change without notice.

ABSOLUTE MAXIMUM RATINGS ($T_C = 25^{\circ}C$, Unless otherwise noted)

Symbol	Parameter	NTMT064N65S3H	Unit	
V _{DSS}	Drain to Source Voltage		650	V
V _{GSS}	Gate to Source Voltage	- DC	±30	
		- AC (f > 1 Hz)	±30	
I _D	Drain Current	- Continuous (T _C = 25°C)	40	А
		- Continuous (T _C = 100°C)	26	
I _{DM}	Drain Current	- Pulsed (Note 1)	120	Α
E _{AS}	Single Pulsed Avalanche Energy (Note 2)		24	mJ
I _{AS}	Avalanche Current (Note 2)		3.7	Α
E _{AR}	Repetitive Avalanche Energy (Note 1)		TBD	mJ
dv/dt	MOSFET dv/dt		100	V/ns
	Peak Diode Recovery dv/dt (Note 3)		20	
P _D	Power Dissipation	(T _C = 25°C)	260	W
		– Derate Above 25°C	2.08	W/°C
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150	°C
TL	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 seconds		300	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Repetitive rating: pulse–width limited by maximum junction temperature.

2. $I_{AS} = 3.7 \text{ A}$, $R_G = 25 \Omega$, starting $T_J = 25^{\circ}\text{C}$.

3. $I_{SD} \le 20 \text{ A}$, $di/dt \le 200 \text{ A/µs}$, $V_{DD} \le 400 \text{ V}$, starting $T_J = 25^{\circ}\text{C}$.

THERMAL CHARACTERISTICS

Symbol	Parameter	NTMT064N65S3H	Unit
$R_{ heta JC}$	Thermal Resistance, Junction to Case, Max.	0.48	°C/W
$R_{ heta JA}$	Thermal Resistance, Junction to Ambient, Max.	45	

PACKAGE MARKING AND ORDERING INFORMATION

Part Number	Top Marking	Package	Packing Method	Reel Size	Tape Width	Quantity
NTMT064N65S3H	NTMT064N65S3H	PQFN88	Tape & Reel	13″	13.3 mm	3000 Units

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

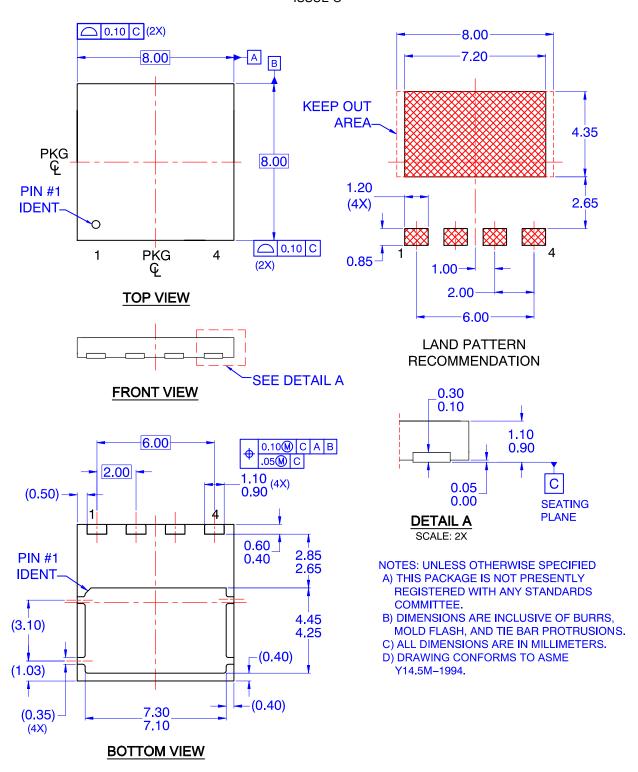
Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
OFF CHARACT	ERISTICS		•			
BV _{DSS} Drain to Source Breakdown Voltage	Drain to Source Breakdown Voltage	$V_{GS} = 0 \text{ V, } I_D = 1 \text{ mA, } T_J = 25^{\circ}\text{C}$	650	_	_	V
	V _{GS} = 0 V, I _D = 1 mA, T _J = 150°C	700	_	_	V	
$\Delta BV_{DSS}/\Delta T_{J}$	Breakdown Voltage Temperature Coefficient	I _D = 10 mA, Referenced to 25°C	-	0.68	_	V/°C
I _{DSS} Zero Ga	ero Gate Voltage Drain Current	V _{DS} = 650 V, V _{GS} = 0 V	_	_	10	μΑ
		V _{DS} = 520 V, T _C = 125°C	_	5.3	_	1
I _{GSS}	Gate to Body Leakage Current	$V_{GS} = \pm 30 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±100	nA
ON CHARACTE	ERISTICS					
V _{GS(th)}	Gate Threshold Voltage	$V_{GS} = V_{DS}$, $I_D = 4.0 \text{ mA}$	2.2	_	4.2	V
R _{DS(on)}	Static Drain to Source On Resistance	V _{GS} = 10 V, I _D = 20 A	_	56	64	mΩ
9FS	Forward Transconductance	V _{DS} = 20 V, I _D = 20 A	_	28	-	S
YNAMIC CHA	RACTERISTICS		•			
C _{iss}	Input Capacitance	V _{DS} = 400 V, V _{GS} = 0 V, f = 1 MHz	_	3860	-	pF
C _{oss}	Output Capacitance		_	58	-	pF
C _{oss(eff.)}	Effective Output Capacitance	V _{DS} = 0 V to 400 V, V _{GS} = 0 V	_	769	_	pF
C _{oss(er.)}	Energy Related Output Capacitance	V _{DS} = 0 V to 400 V, V _{GS} = 0 V	_	123	_	pF
Q _{g(tot)}	Total Gate Charge at 10 V	$V_{DS} = 400 \text{ V}, I_{D} = 20 \text{ A}, V_{GS} = 10 \text{ V}$	_	77	_	nC
Q _{gs}	Gate to Source Gate Charge	(Note 4)	_	20	_	nC
Q _{gd}	Gate to Drain "Miller" Charge		_	19	_	nC
ESR	Equivalent Series Resistance	f = 1 MHz	_	0.7	_	Ω
WITCHING CH	HARACTERISTICS					
t _{d(on)}	Turn-On Delay Time	V _{DD} = 400 V, I _D = 20 A,	_	30	_	ns
t _r	Turn-On Rise Time	$V_{GS} = 10 \text{ V}, R_g = 4.7 \Omega$ (Note 4)	-	12	-	ns
t _{d(off)}	Turn-Off Delay Time		-	83	-	ns
t _f	Turn-Off Fall Time		_	3	-	ns
OURCE-DRAI	N DIODE CHARACTERISTICS		•			•
I _S	Maximum Continuous Source to Drain Diode Forward Current		_	_	40	Α
I _{SM}	Maximum Pulsed Source to Drain Diode Forward Current		_	-	120	Α
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} = 0 V, I _{SD} = 20 A	-	-	1.2	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _{SD} = 20 A,	_	353	-	ns
Q _{rr}	Reverse Recovery Charge	$dI_F/dt = 100 \text{ A/}\mu\text{s}$	_	5.9	-	μС

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Essentially independent of operating temperature typical characteristics.

PACKAGE DIMENSIONS

PQFN4 8X8, 2P CASE 483AP ISSUE O



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PUBLICATION ORDERING INFORMATION

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